CALL FOR ABSTRACTS

IEEE Symposium on Reliability for Electronics and Photonics Packaging (REPP)

November 7-8, 2024 • Purdue University, Indiana, USA

The fifth annual REPP symposium will take place at the Silicon Valley of the Midwest, Purdue University. It will focus on quantified reliability, accelerated testing and probabilistic assessments of the useful lifetime of electronic, photonic, MEMS and MOEMS materials, assemblies, packages and systems in electronics and photonics packaging. This includes failure modes, mechanisms, testing schemes, accelerated testing, stress levels, and environmental stresses. The intent is to bring together electrical, reliability, materials, mechanical, and computer engineers and applied scientists to address the state-of-the-art in all the interconnected fields of electronic and photonic packaging, with an emphasis on various reliability-related aspects: design-for-reliability, manufacturing, reliability modeling and accelerated testing.

- Abstracts or proposals should include a title and a summary of 200-500 words with one or two optional figures or diagrams, clearly showing the relationship of the talk to the topics of the Symposium

- Travel grants of $1,000 are available for grad students presenting their work

- **Deadline to submit is September 15, 2024** *(Acceptance of proposed presentations will be announced by September 20, 2024)*

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Submit abstracts here:
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Questions? Contact Tiwei Wei:
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